

PATENT COOPERATION TREATY

Fron	the.	Japan Patent Off	ice (INTERNATI	ONAL SEARCHING	G A	UTHORITY)			
To: Agent for applicant			PCT						
Mr. Chikara MIYAŻAKI					101				
Address: Nishimura Building, 6-5, Tanimachi 1-chome, Chuo-ku, Osaka-shi, Osaka 540-0012, Japan			WRITTEN OPINION OF THE INTERNATIONAL SEARCHING AUTHORITY (Implementing Regulation 40 bis) (PCT Rule 43bis.1)						
						Date of mailing			
						(day/month/year)	24. 5. 2005		
Ap	plica	int's or agent's fil	e reference			FOR FURTHER A	CTION		
	F63	IPCT					See paragraph 2 below		
Int	ernat	ional application	No.	International filing	g da	te (day/month/year)	Priority date (day/me	onth/yea	ır)
	PC7	Г/JP2005/001418	3	01. 02. 2005			27. 02. 2004		
Int	ernat	ional Patent Clas	ssification (IPC)	Int. Cl ⁷ H01G 4/1	2	H01G 4/252 H01G	4/30		
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Ap	plica	int							
	Μι	ırata Manufa	cturing Co.,	Ltd.					
1									
1.	Thi	s opinion contain	ns indications rela	iting to the following	g ite	ems:			
	X	Box No. I	Basis of the opi	nion					
		Box No. II	Priority	•					
		Box No. III	Non-establishm	ent of opinion with r	rega	ard to novelty, inventiv	e step and industrial ap	plicabi	lity
		Box No. IV	Lack of unity of	f invention					
	×	Box No. V				(a)(i) with regard to no s supporting such state	ovelty, inventive step o ment	r indust	rial
		Box No. VI	Certain docume	ents cited					
		Box No. VII	Certain defects	in the international a	ppl	lication			
		Box No. VIII	Certain observa	tions on the internati	iona	al application			
2.	FU	RTHER ACTIO	ON						
	Inte Aut	rnational Prelimi hority other than	inary Examining at this one to be the	Authority ("IPEA") e IPEA and the chose	exce en I	ept that this does not a	considered to be a writ pply where the applicanternational Bureau undered.	nt choos	ses an
	IPE.	A a written reply	together, where	appropriate, with am	end	lments, before the expi	, the applicant is invite ration of 3 months froi ity date, whichever exp	n the da	ite of
	For	further options,	see Form PCT/IS	A/220					
3.	For	further details, s	see notes to Form	PCT/ISA/220					
Da	te of	completion of th	is opinion	10. 05. 2005					
Na	me a	nd mailing addre	ess of the ISA/JP	20, 00, 2000		Authorized office	er	5R	3387
		.Jai	pan Patent Of	ffice		Masafumi YA	MADA [<u> </u>
3-4	-3, K	-	niyoda-ku, Tokyo			-	3-3581-1101 Ext. 3565		

WRITTEN OPINION OF THE INTERNATIONAL SEARCHING AUTHORITY

International application No. PCT/JP2005/001418

Box	No.	I Basis of this opinion
1.		regard to the language, this opinion has been established on the basis of the international application in the language in the it was filed, unless otherwise indicated under this item.
		This opinion has been established on the basis of a translation from the original language into the following language, which is the language of a translation furnished for the purpose of international search (under Rules 12.3 and 23.1(b)).
2.		n regard to any nucleotide and/or amino acid sequence disclosed in the international application and necessary to the med invention, this opinion has been established on the basis of:
a.	ty	pe of material
		a sequence listing
		table(s) related to the sequence listing
ь.	fo	rmat of material
		in written format
		in computer readable form
c.	tir	ne of filing/furnishing
		contained in the international application as filed.
		filed together with the international application in computer readable form.
		furnished subsequently to this Authority for the purposes of search.
3.		In addition, in the case that more than one version or copy of a sequence listing and/or table relating thereto has been filed or furnished, the required statements that the information in the subsequent or additional copies is identical to that in the application as filed or does not go beyond the application as filed, as appropriate, were furnished.
4.	Ađđ	itional comments:
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WRITTEN OPINION OF THE INTERNATIONAL SEARCHING AUTHORITY

International application No. PCT/JP2005/001418

Box No. V			bis.1(a)(i) with regard to novelty, in tions supporting such statement	ventive step or industrial
1. Statement				
Novelt	y (N)	Claims	5, 7-9, 11	YES
		Claims	1-4, 6, 10	NO
Inventi	ive step (IS)	Claims	7-9	YES
		Claims	1-6, 10, 11	NO
Industr	rial applicability (IA)	Claims	_1-11	YES
		Claims		NO

2. Citations and explanations:

Document 1: JP 8-97075 A (Murata Manufacturing Co., Ltd.)

April 12, 1996; all pages; Fig. 1

Document 2: JP 8-203770 A (Murata Manufacturing Co., Ltd.)

August 9, 1996; Paragraphs [0010]-[0025]; Fig. 1

Document 3: JP 8-37127 A (Matsushita Electric Industrial Co., Ltd.)

February 6, 1996; Claim 4; Paragraph [0014]; Figs. 1-3

Document 4: JP 2001-200163 A (Matsushita Electric Works, Ltd.)

July 24, 2001; Claims

• Claims 1-6, 10, and 11

Document 1 discloses a monolithic ceramic electronic component and a method for manufacturing such a component. The monolithic ceramic electronic component is manufactured as follows: a conductive paste containing glass is applied onto a ceramic sintered body, small pieces of silver foil are bonded to the conductive paste, a first electrode layer (corresponding to "the sintered electrode layer") and a silver foil-bonded layer lying thereover are formed by baking the resulting conductive paste, and a plated Ni layer (corresponding to "the intermediate electroplated layer") and a plated Sn layer are formed on the silver foil-bonded layer in that order.

Since the plated Ni layer is formed on the silver foil piece-bonded layer, silver contained in the silver foil-bonded layer is determined to correspond to "the metals acting as seeds" cited in Claims 1 and 6.

Accordingly, the invention claimed in Claims 1-4, 6, and 10 lacks novelty and inventive step.

Document 2 discloses a monolithic ceramic electronic component and a method for manufacturing such a component. This monolithic ceramic electronic component is manufactured as follows: a first electrode layer (corresponding to "the sintered electrode layer") is formed by applying a conductive paste containing glass onto a ceramic sintered body and then baking the conductive paste, a second electrode layer is formed on a portion thereof using a conductive resin, and a plated Ni layer (corresponding to "the intermediate electroplated layer") and a plated Sn layer are formed over the first and second electrode layers in that order.

The use of the conductive resin containing metal powder made of copper (Cu) or tin (Sn) is known as disclosed in Documents 3 and 4.

Therefore, those skilled in the art can readily appreciate that the invention claimed in Claims 1-6, 10, and 11 can be made using the above known technique and the conductive resin, disclosed in Document 2, containing metal powder made of tin or the like to manufacture the monolithic ceramic electronic component disclosed in Document 2.

Accordingly, the invention claimed in Claims 1-6, 10, and 11 lacks inventive step.

· Claims 7-9

The invention claimed in Claims 7-9 is not disclosed in any of Documents 1-4 and is not therefore obvious to those skilled in the art.